









Release Date: 19 December 2023 Version: A1.4

PRODUCT DATASHEET



- ► PTH/THT Lamp
- ➤ 3mm Cylindrical 3.8t
- ► True Green (525nm)

NOG16L93Z (Bulk) N0G16L93ZT (Taping)



3mm Cylindrical Lamp





FEATURES:

- Package: PTH/THT Lamp 3mm Cylindrical 3.8t
- Forward Current: 20mA Forward Voltage (typ.): 3.2V
- Luminous Intensity (typ.): 650mcd @20mA
- Colour: True Green
- Dominant Wavelength (typ.): 525nm
- Viewing Angle: 170°
- Electrostatics Discharge (ESD): 2000V
- **Materials:**

 - Resin: Epoxy (Green Diffused)
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- **Grouping Parameters:**
 - Forward voltage
 - Luminous intensity
 - Dominant wavelength
- Soldering Methods: Hand; Soldering Heat (DIP)
- Packing: 500pcs/Bulk; 2000pcs/Taping

3 mm Cylindrical Lamp

APPLICATIONS:

- Indicator
- Switch
- Signal Light



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	30	mA
Peak Forward Current Duty 1/10@1KHz	I _{FP}	100	mA
Reverse Current @5V	IR	10	μА
Power Dissipation	P _D	85	mW
Electrostatics Discharge	ESD	2000	V
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

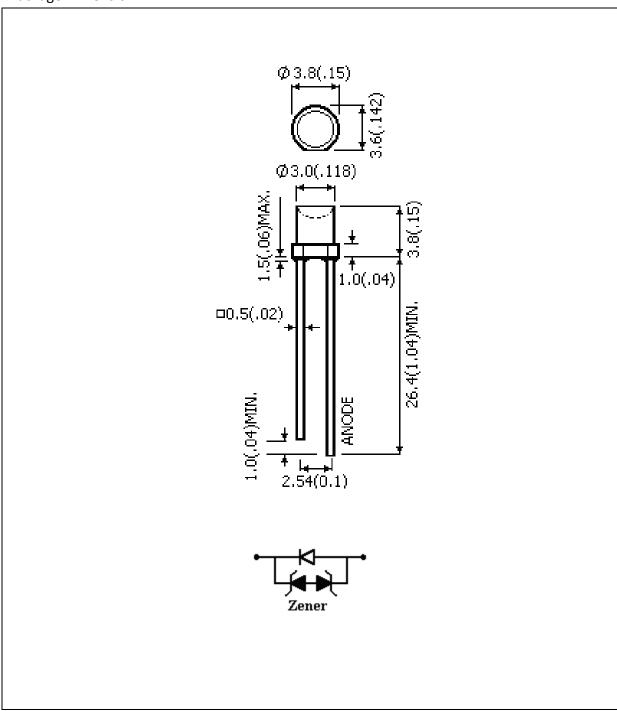
Parameter Symbol		Values			Unit	Test
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V_{F}	2.9	3.2	3.6	V	I _F =20mA
Luminous Intensity	Iv	500	650	850	mcd	I _F =20mA
Dominant Wavelength	λ_{D}	515	525	530	nm	I _F =20mA
Peak Wavelength	λ_{P}		525		nm	I _F =20mA
Spectral Line H-Width	Δλ		36		nm	I _F =20mA
Viewing Angle	2θ _{1/2}		170		deg	I _F =20mA

^{1.} Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V



OUTLINE DIMENSION:

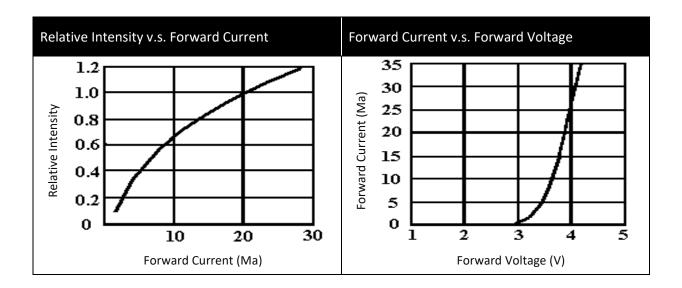
Package Dimension:

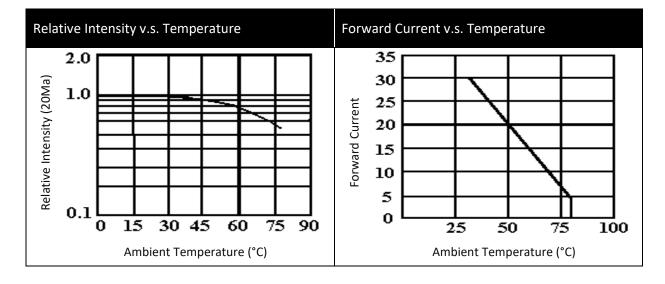


- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.25mm, unless otherwise noted.



ELECTRO-OPTICAL CHARACTERISTICS:





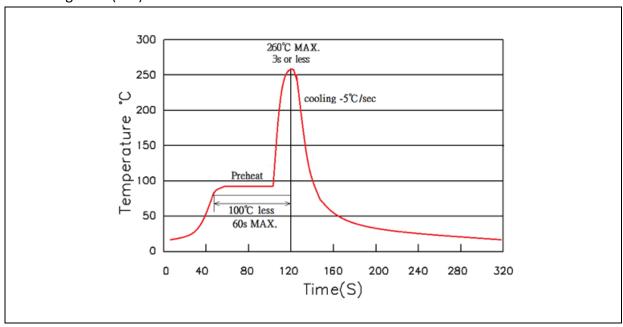


RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds ± 1 sec.

Soldering Heat (DIP):

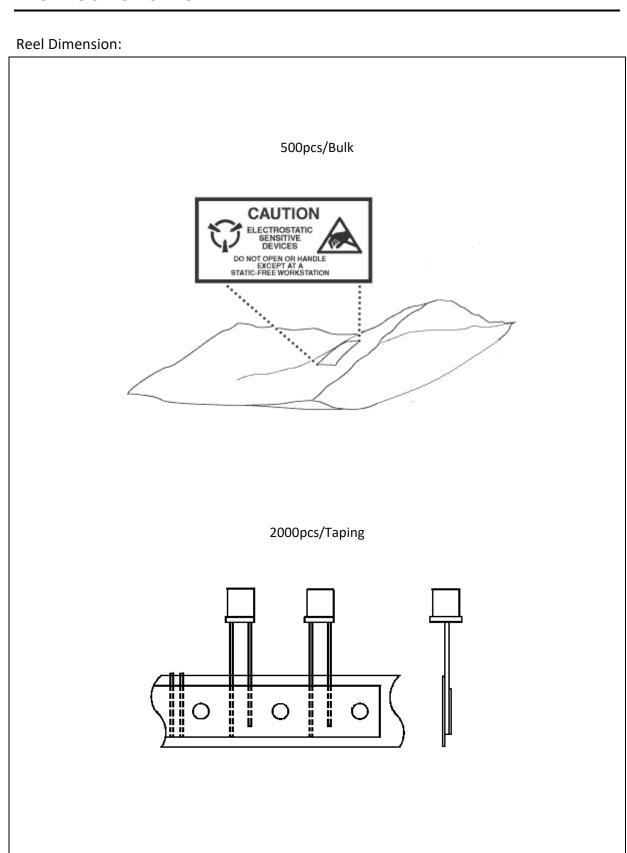


Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a year. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

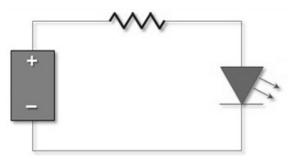
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision	
A1.0	04/08/2015	Datasheet set-up.	
A1.1	21/09/2015	Update solder profile.	
A1.2	23/10/2015	Revise diode direction.	
A1.3	24/03/2023	Revise wavelength range.	
A1.4	19/12/2023	Revise storage condition.	